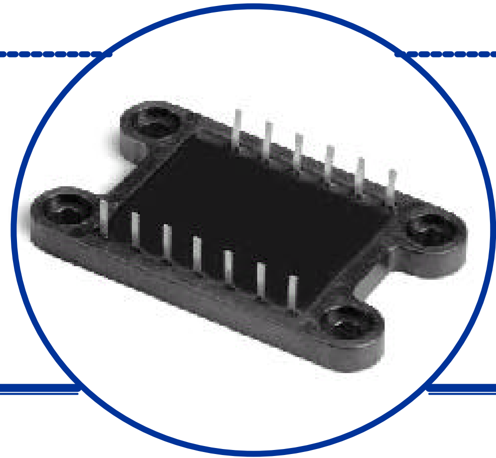
Power Modules

Sales Aid



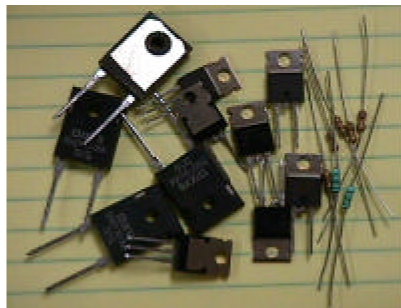
Highly compact and efficient alternative to the individual discrete power semiconductor approach

ISO 9001 AND QS-9000 certified

Features / *Benefits*

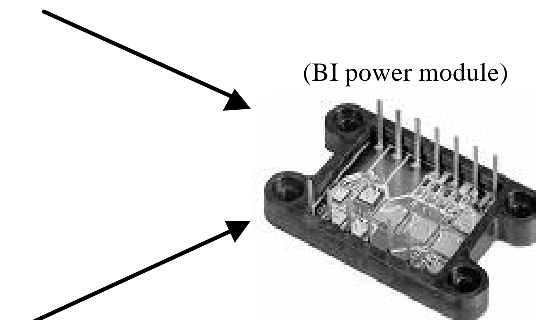
Features	Benefits
Ceramic based substrate with heavy copper traces (Direct Bonded Copper)	*Excellent current path, low thermal resistance, high voltage isolation to heat sink.*
BI Solder die attach process achieves greater than 95% solder coverage on die to substrate interface	*Improve thermal conduction, resilient to temperature shock*
Closely packaged components achieved through die attached and wire bonding	*Reduced stray inductance, cleaner signals, reduced EMI and greater switching speed.*
Simplified single package	*Easy heat sink design and reduced assembly time.*
Internal temperature sensing	*Allow for faster response time to circuit overload, greater circuit protection*

BI Technologies creative packaging allows for design simplification



(Individual components)

(BI power module)



General Note
BI Technologies reserves the right to make changes in product specification without notice or liability.
All information is subject to BI's own data and is considered accurate at the time of publishing.

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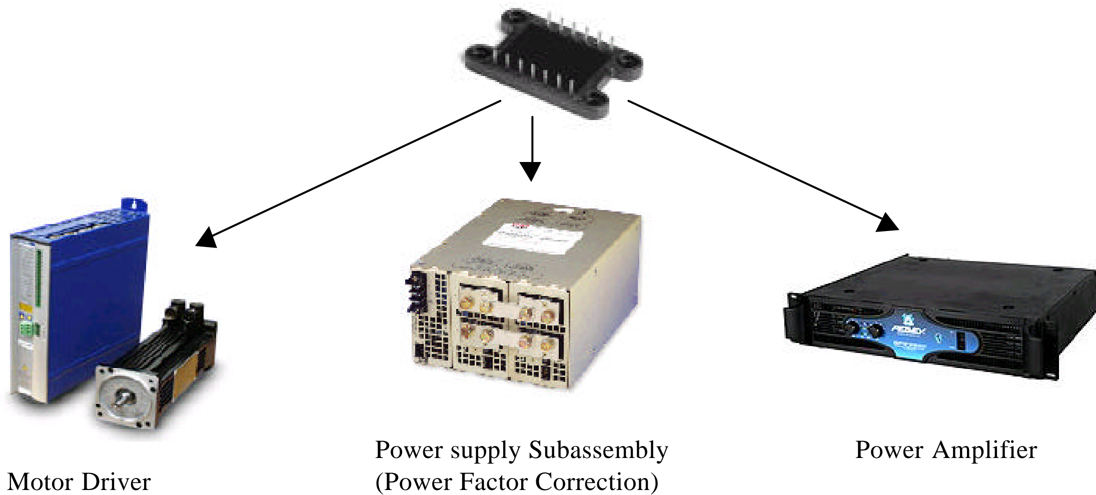
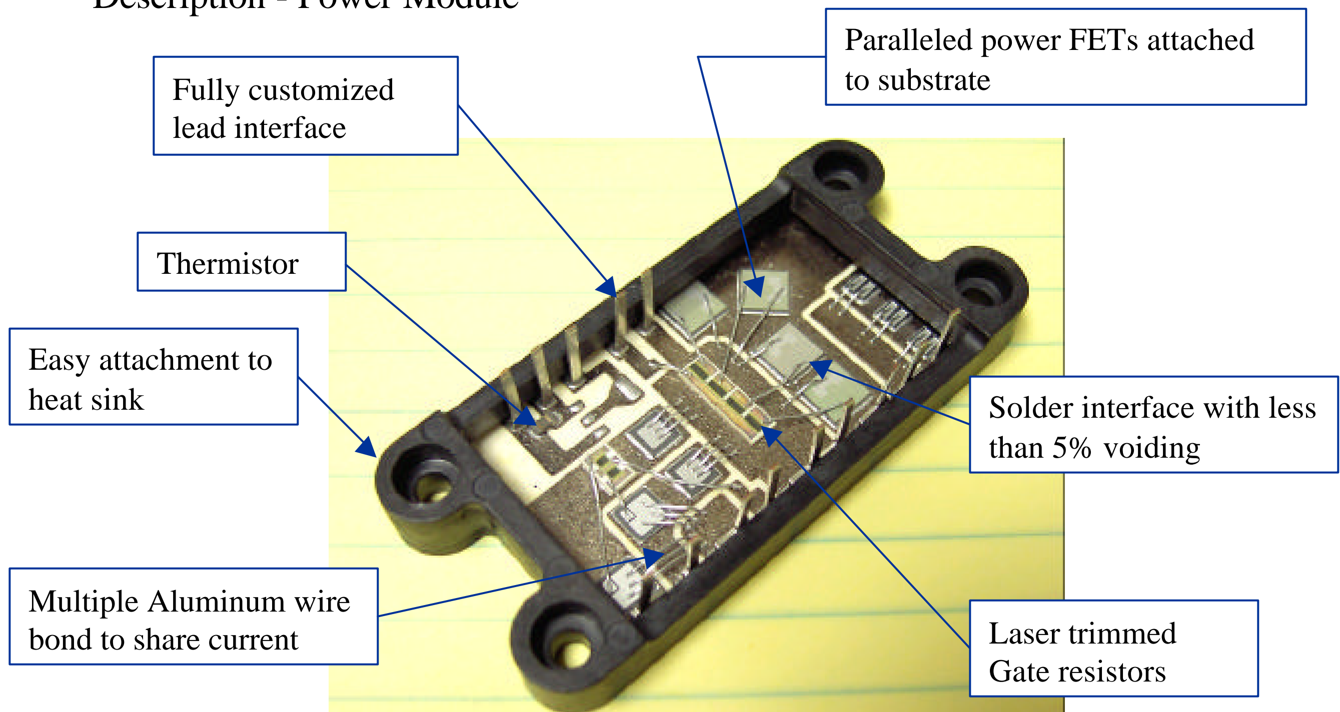
Applications



Description - Power Module



Contact BI Technologies

For assistance with your application or price and delivery information contact BI Technologies product Marketing at (714) 447-2345, by fax (714) 388-0046, by email: sales@bitechnologies.com